



iEDX-150T

Type : sp10, sp30, sp40, mp30, mp40
Coating/Plating Thickness Analyzer

X-ray tube	◆ Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA
Detection System	◆ Si-Pin Diode, (Option : Proportional Counter, SDD)
Energy Resolution	◆ Si-Pin Diode : 149eV FWHM at Mn K α Option < P C : 800eV FWHM at Mn K α SDD : 125eV FWHM at Mn K α
Collimator	◆ 0.3 Collimator (Option : 0.05, 0.1, 0.2, 0.5, 1mm) Manual / Auto Changing Stage
Detection Element	◆ Al(13) - U(92)
Sample Type	◆ Solid / Liquid / Powder, Multi-Layer
Size of the sample chamber	◆ 390mm X 410mm X 100mm (W x D x H) ◆ Auto / Manual Stage Mode
Key Features	◆ Plating thickness measurement : General, Rh, Pd, Au, Ag, Sn, Ni ◆ Film thickness measurement of multilayer thin films. (up to 5 Layer)
Camera Magnification	◆ 40~80 x
Safety	◆ 3 point interlock
Type of Report	◆ Excel, PDF / output ◆ Custom form
Key Benefits	◆ Film thickness measurement of multilayer thin films. (up to 5 Layer) ◆ Convenient stage control ◆ Multi-point measurement possible ◆ RoHS Screening(Optional) ◆ Remote Support by Online
Application	◆ Product screening international environmental regulations (RoHS, WEEE, ELV compliant) ◆ Hazardous material(Cr, Br, Cd, Hg, Pb, Cl, Sb, Sn, S) Screening equipment ◆ Plating analysis automobile parts, Electronic circuit board (PCB), Such as a capacitor ◆ Analysis of single-layer, Multi-layer, Alloy plating ◆ Thickness with Composition Ratio can be measure on time in alloy plating

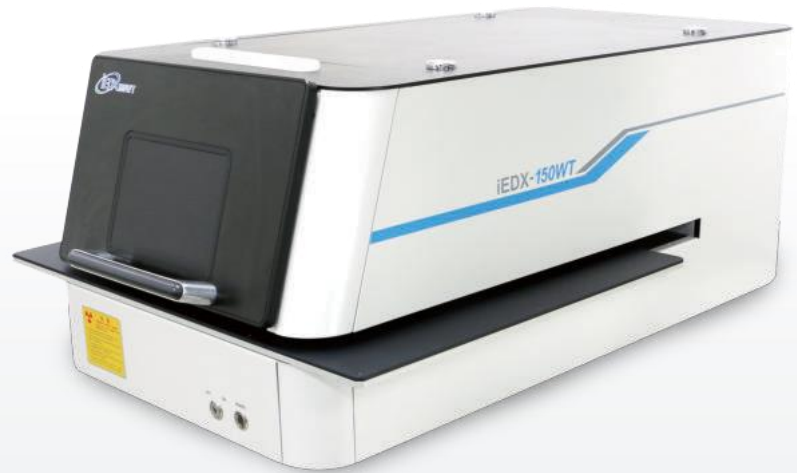


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iEDX-150WT

Type : sp10, sp30, sp40, mp30, mp40
Coating Thickness Analyzer / Large scale PCB

X-ray tube	• Mo/Rh/W/Ag Target(Option), 50kVp, 1mA
Detection System	• Si-Pin Diode. (Option : Proportional Counter, SDD)
Energy Resolution	• Si-Pin Diode : 149eV FWHM at Mn K α Option < P C : 800eV FWHM at Mn K α SDD : 125eV FWHM at Mn K α
Collimator	• 0.3 Collimator (Option : 0.05, 0.1, 0.2, 0.5, 1mm) Manual / Auto Changing Stage
Detection Element	• Al(13) - U(92)
Sample Type	• Multi-Layer, Wide PCB
Size of the sample chamber	• 300mm X 282mm X 45mm (W x D x H) • Auto / Manual Stage Mode
Key Features	• Plating thickness measurement : General, Rh, Pd, Au, Ag, Sn, Ni • Film thickness measurement of multilayer thin films. (up to 5 Layer)
Camera Magnification	• 40~80 x
Safety	• 3 point interlock
Type of Report	• Excel, PDF / output • Custom form • Film thickness measurement of multilayer thin films. (up to 5 Layer)
Key Benefits	• Convenient stage control • Multi-point measurement possible • RoHS Screening(Option) • Remote Support by Online
Application	• Product screening international environmental regulations (RoHS, WEEE, ELV compliant) • Hazardous material(Cr, Br, Cd, Hg, Pb, Cl, Sb, Sn, S) Screening equipment • Plating analysis automobile parts, Electronic circuit board (PCB), Such as a capacitor • Analysis of single-layer, Multi-layer, Alloy plating • Thickness with Composition Ratio can be measure on time in alloy plating



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iEDX-1 50 μ T

High Performance Coating Thickness Analyzer

X-ray tube	<ul style="list-style-type: none"> Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA
Detection System	<ul style="list-style-type: none"> SDD (Silicon Drift Detector)
Energy Resolution	<ul style="list-style-type: none"> 125eV FWHM at Mn Kα
Collimator	<ul style="list-style-type: none"> Poly capillary optics (50~100μm)
Detection Element	<ul style="list-style-type: none"> Al(13) - U(92)
Sample Type	<ul style="list-style-type: none"> Solid / Liquid / Powder, Multi-Layer
Size of the sample chamber	<ul style="list-style-type: none"> 390mm X 410mm X 100mm (W x D x H)
Key Features	<ul style="list-style-type: none"> Auto / Manual Stage Mode Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni Film thickness measurement of multilayer thin films. (up to 5 Layer)
Camera Magnification	<ul style="list-style-type: none"> 40~80 x
Safety	<ul style="list-style-type: none"> 3 point interlock
Type of Report	<ul style="list-style-type: none"> Excel, PDF / output Custom form
Key Benefits	<ul style="list-style-type: none"> Micro focused measuring point(70μm) using capillary optics Film thickness measurement of multilayer thin films. (up to 5 Layer) Convenient stage control Multi-point measurement possible Remote Support by on line
Application	<ul style="list-style-type: none"> Plating thickness measurement special, ENEPIG, Pd-Ni, Rh etc. Plating analysis automobil parts, Electronic circuit board (PCB), Such as a capacitor Analysis of single-layer, Multi-layer, Alloy plating Thickness with Composition Ratio can be measure on time in alloy plating



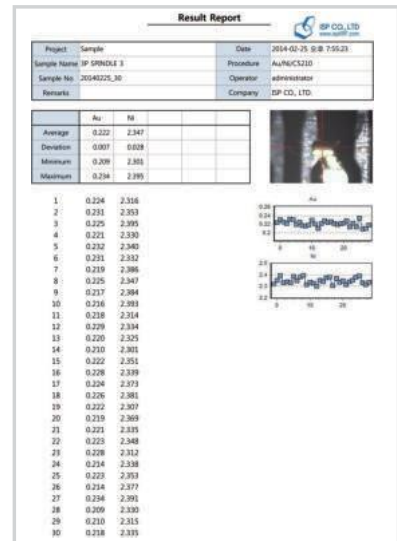
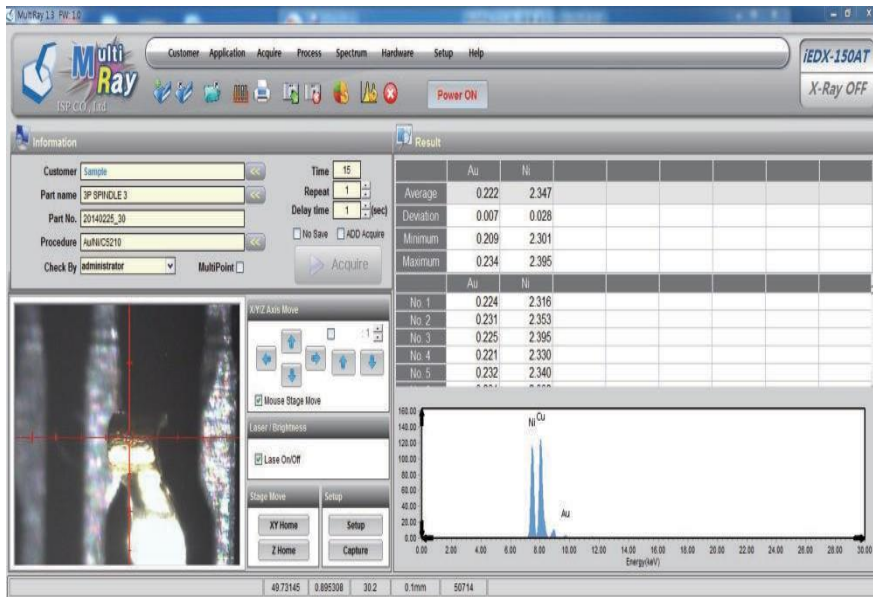
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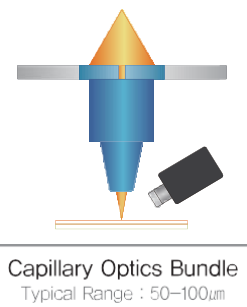
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Coating Thickness Analysis Software MultiRay



Report results of measurement plating thickness

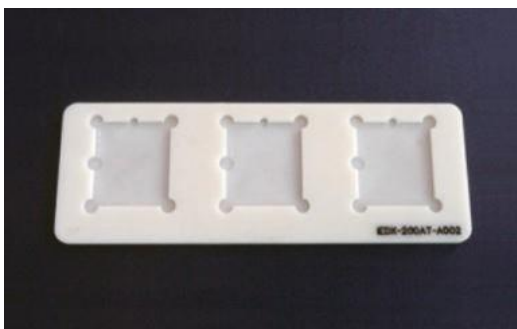
- ◆ Multi-layer thickness analysis
- ◆ Simple plating layer define
- ◆ Convenient parameters setup
- ◆ Fundamental Parameters method, calibration curve method, absorption method support
- ◆ Define the concentration with elements on alloy layer
- ◆ PDF, EXCEL save function



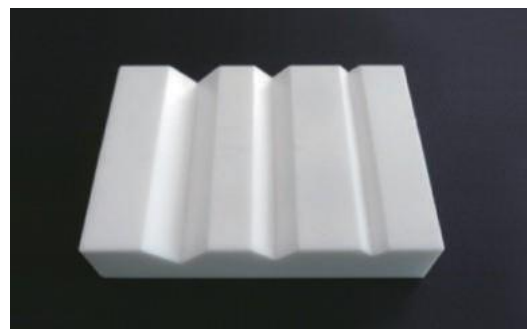
〈Thickness Standard〉



〈Polycapillary & Monicapillary Optics〉



〈Coating thickness standard block〉



〈Coating thickness sample block〉



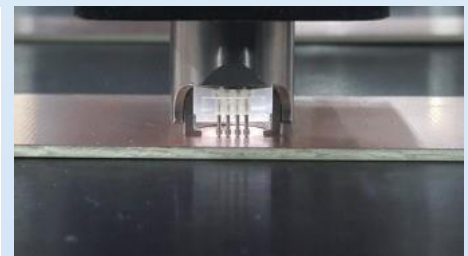
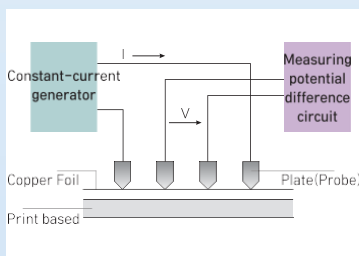


◆ Measure copper coating or plating thickness of the top layer on PCB by EN14571 standard with micro resistance method

iTG-B10

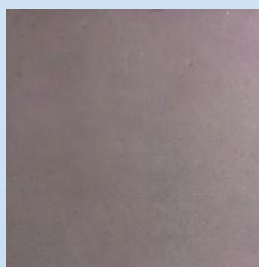
Copper Thickness Gauge

Measurement Method		4 Probe micro Resistance
Sample		Copper layer on PCB
Thickness Range	RANGE 1	0.1~10 μ m
	RANGE 2	10~120 μ m
Accuracy		\pm 1% with reference to standards
Measuring Time		1 sec/point
Display Size		8 inch
Battery		Ion battery recharge
Memory capacity		Unlimited
Export of Results		Wireless printer, Excel, E-mail
Operating System		Android 4.4
Communication System		Bluetooth

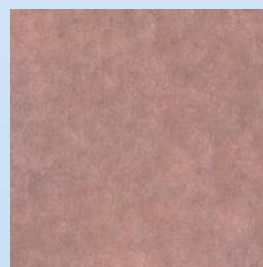


◆ 4 Probe micro resistance method is most effective way of accurate and precise measurement for copper layer on PCB

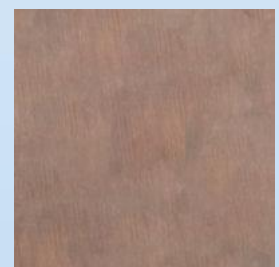
Standard Sample



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<11.5um Sample>



<31.7um Sample>

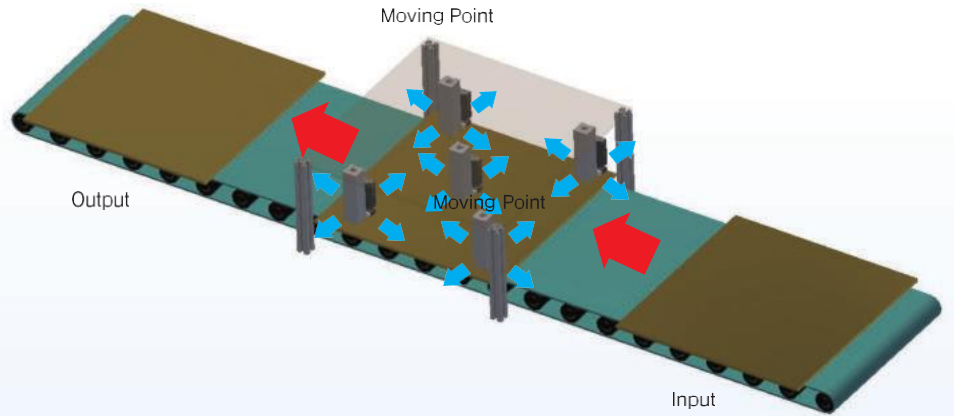


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iTG-C10

In Line Copper Thickness Gauge

Measurement Method	4 Probe micro Resistance
Sample	Copper layer on PCB
Thickness Range	RANGE 1 0.1~10 μ m
	RANGE 2 10~120 μ m
Accuracy	\pm 1% with reference to standards
Number of Measuring point	Up to 20 point
Report	Excel, PDF
Operating System	Window 7 or more
Interface	USB 2.0



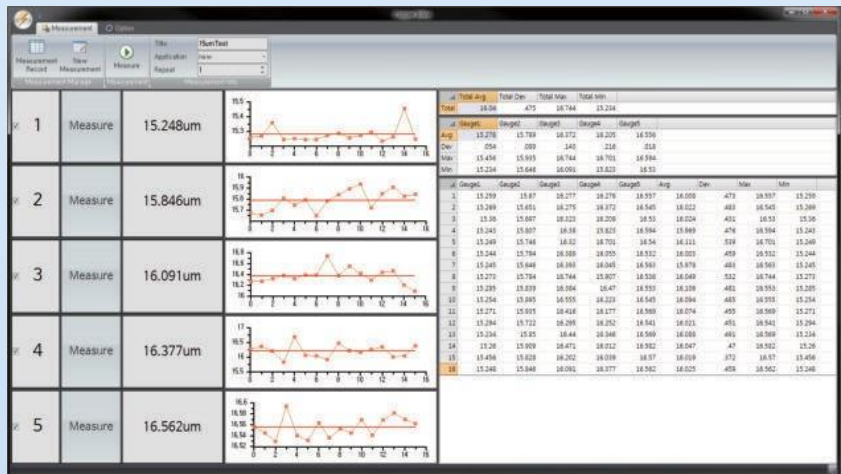
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User Interface



Reel to Reel

In-line Plating Thickness Gauge



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X-ray tube

- Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA

Detection System

- SDD (Silicon Drift Detector)
- P.C(Proportional Counter)

Collimator

- Poly capillary optics

Detection Element

- Al(13) - U(92)

Key Features

- Auto / Manual Stage Mode
- Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni
- Film thickness measurement of multilayer thin films. (up to 5 Layer)

Camera Magnification

- 40~80 x

Type of Report

- Excel, PDF / output
- Custom form

Application

- Plating thickness measurement special, ENEPIG, Pd-Ni, Rh etc.
- Plating analysis automobil parts, Electronic circuit board (PCB),
Such as a capacitor
- Analysis of single-layer, Multi-layer, Alloy plating
- Thickness with Composition Ratio can be measure on time in alloy plating



iEDX-750T

Plating Thickness Analyzer

X-ray tube

- ◆ Mo/Rh/W/Ag Target(option), 50kVp, 1mA

Detection System

- ◆ SDD(Silicon Drift Detector)

Energy Resolution

- ◆ 125eV FWHM at Mn K α

Collimator

- ◆ Poly Capillary Optics(FWHM 15~30 μ m)

Detection Element

- ◆ Al(13)~U(92)

Sample Type

- ◆ Wide PCB

Sample Size

- ◆ Max : 510 x 415

Equipment Size

- ◆ 2600mm x 1350mm x 2050mm(W x D x H)

Utility

- ◆ Power : Single-Phase 220V, 4kw
- ◆ Air Pressure : 5kgf

Key Features

- ◆ Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni
- ◆ Film thickness measurement of multilayer thin films.(up to 5 Layer)

Camera Magnification

- ◆ 40~80 Magnification

Safety device of Radioactivity

- ◆ Cut-off device for an automatic 3

Type of Report

- ◆ Excel, PDF / output
- ◆ Custom form

Key Benefits

- ◆ Film thickness measurement of multilayer thin films, (up to 5 Layer)
- ◆ Convenient stage control
- ◆ Multi-point measurement possible

Application

- ◆ ENIG, ENEPIG
- ◆ Electronic circuit board (PCB)
- ◆ The analysis of the exact content when measuring plating thickness



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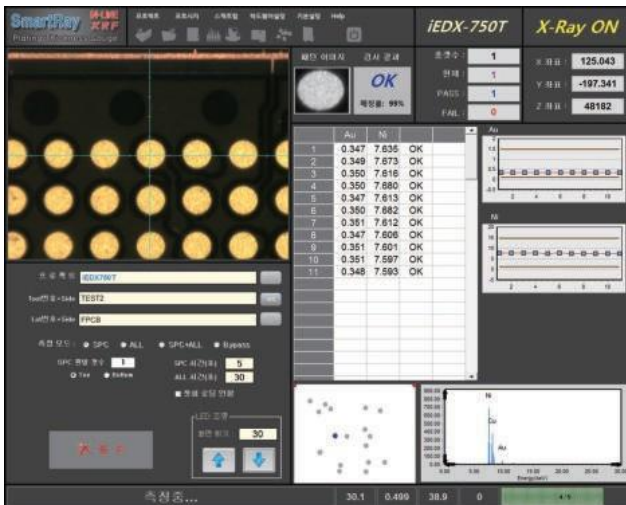
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Plating Thickness Program iEDX-750T

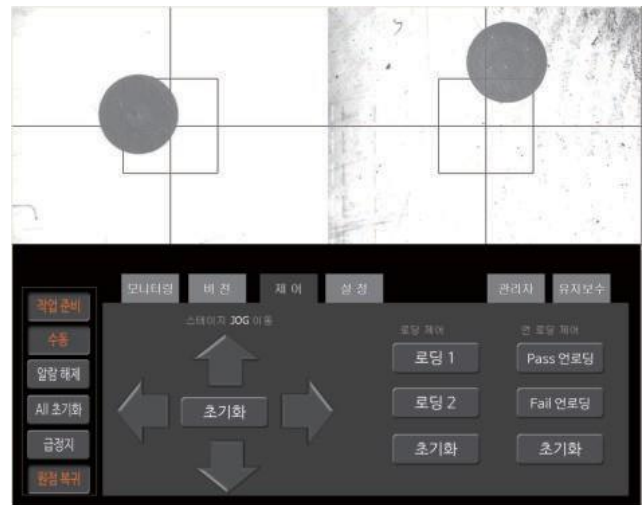
Main UI



Function

- ◆ Multipoint automatic measurement
- ◆ Sample Pattern Matching Test
- ◆ Display Result Pass/Fail
- ◆ Display Spectrum

Align UI



Function

- ◆ Automatic / manual control
- ◆ Alarm Reset
- ◆ initialization
- ◆ Emergency stop and home return
- ◆ Align status Monitoring
- ◆ Stage control

Option

Cartridge type Loader & Unloader

